Different Pin Marks with new Mold Cavity Design affecting products in packages T/LQFP-144 at Infineon Malacca, Malaysia.
## Comparison in existing/new procedure (overview)

<table>
<thead>
<tr>
<th>Existing</th>
<th>New</th>
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</thead>
<tbody>
<tr>
<td>2x Ejector pins to release package from cavity</td>
<td>2x Ejector pins to release package from cavity. The pins come with ID marks</td>
</tr>
<tr>
<td>2x protrusion pins with ID marks</td>
<td></td>
</tr>
</tbody>
</table>
Before:

2x Ejector pin marks
2x Intrusion marks

2x Ejector pins to release package from cavity. The pins come with ID marks

After:

2x Ejector pin marks

Mold Cavity | Package
---|---
2x Ejector pins to release package from cavity | Appear as 2 intrusion marks. Not functional to customer

2x protrusion pins with ID marks | Appear as 2 intrusion marks with ID. Not functional to customer
ENERGY EFFICIENCY
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